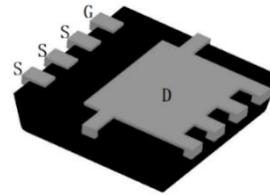


FEATURES

- Drain-Source Withstand Voltage: 60V
- Max. $R_{DS(on)}$: 8.2 m Ω @ $V_{GS}=10V$
13.5 m Ω @ $V_{GS}=4.5V$
- Automotive applications
- AEC-Q101 Qualified
- Excellent ON resistance
- General footprint package PDFN3333-8L
- 100% Rg and Avalanche tested
- MSL1

PRODUCT APPEARANCE


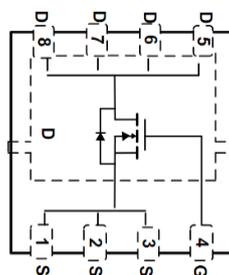
PDFN3333-8L

DESCRIPTION

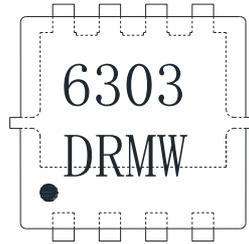
The SNM068R2DRAQ is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in high performance automotive DC-DC conversion, power switch and charging circuit. Standard Product SNM068R2DRAQ is in compliance with RoHS.

Applications:

- Automotive systems
- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

PIN CONFIGURATION


Top view

MARKING


6303 = Device Code
 DR = Special Code
 M = Month
 W = Week

LIMITING VALUES

Parameter	Symbol	Condition	Value	Unit
Drain-Source Voltage	V_{DS}		60	V
Gate-Source Voltage	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_C=25^\circ\text{C}$	60	A
		$T_C=100^\circ\text{C}$	42	A
Pulsed Drain Current ⁽³⁾	I_{DM}		154	A
Continuous Drain Current	I_D	$T_A=25^\circ\text{C}$	13	A
		$T_A=100^\circ\text{C}$	9	A
Avalanche Energy $L=0.3\text{mH}$	E_{AS}		54	mJ
Power Dissipation ⁽²⁾	P_D	$T_C=25^\circ\text{C}$	60	W
		$T_C=100^\circ\text{C}$	30	W
Power Dissipation ⁽¹⁾	P_D	$T_A=25^\circ\text{C}$	2.7	W
		$T_A=100^\circ\text{C}$	1.3	W
Operating Junction Temperature	T_J		-55 to 175	$^\circ\text{C}$
Storage Temperature Range	T_{STG}		-55 to 175	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Single Operation					
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ⁽¹⁾	Steady State	R _{θJA}	45	56	°C/W
Junction-to-Case Thermal Resistance ⁽²⁾	Steady State	R _{θJC}	2.0	2.5	

ELECTRONICS CHARACTERISTICS

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0 V, I _D = 250μA	60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	BV _{DSS} /T _J			29.5		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} = 0V, T _J =25°C			10	μA
		V _{DS} =60V, V _{GS} = 0V, T _J =125°C			250	μA
Gate-to-source Leakage Current	I _{GSS}	V _{DS} =0 V, V _{GS} = 20V			100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} , I _D = 250μA	1.3	1.7	2.1	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J			-4.7		mV/°C
Drain-to-source On-resistance ⁽⁴⁾	R _{DS(on)}	V _{GS} =10V, I _D =25A		6.5	8.2	mΩ
		V _{GS} =4.5V, I _D =25A		10.2	13.5	
CHARGES, CAPACITANCES AND GATE RESISTANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0V, f = 1.0MHz, V _{DS} =25V		1200		pF
Output Capacitance	C _{OSS}			520		
Reverse Transfer Capacitance	C _{RSS}			54		
Total Gate Charge ⁽⁵⁾	Q _{G(TOT)}	V _{GS} =10V, V _{DS} = 48V, I _D = 25A		21.6		nC
Total Gate Charge ⁽⁵⁾	Q _{G(TOT)}	V _{GS} =4.5V, V _{DS} = 48V, I _D = 25A		11.7		nC

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Gate-to-Source Charge ⁽⁵⁾	Q_{GS}	$V_{GS}=10V,$ $V_{DS}=48V, I_D=25A$		2.9		nC
Gate-to-Drain Charge ⁽⁵⁾	Q_{GD}			5.9		nC
Gate Resistance	R_g	$f=1MHz$		1.3		Ω
SWITCHING CHARACTERISTICS ⁽⁵⁾						
Turn-On Delay Time	$t_d(ON)$	$V_{GS}=4.5V,$ $V_{DS}=48V,$ $I_D=25A, R_G=1\Omega$		6.6		ns
Rise Time	t_r			37.8		
Turn-Off Delay Time	$t_d(OFF)$			16		
Fall Time	t_f			15.6		
Body Diode Reverse Recovery Time	t_{rr}	$I_F=25A,$ $dI/dt=100A/\mu s$		22.3		ns
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F=25A,$ $dI/dt=100A/\mu s$		12.7		nC
BODY DIODE CHARACTERISTICS						
Forward Voltage ⁽⁴⁾	V_{SD}	$V_{GS}=0V, I_S=25A$	0.5	0.86	1.2	V

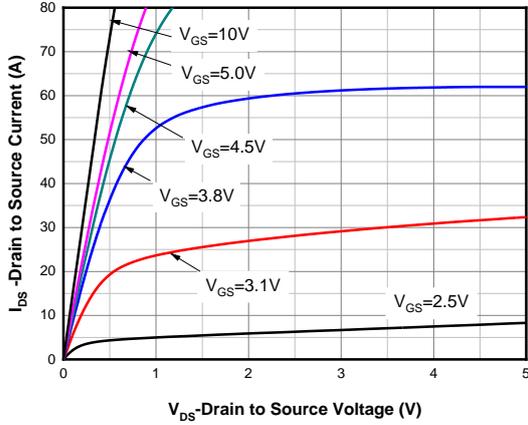
($T_J=25^\circ C$, unless otherwise noted.)

Note:

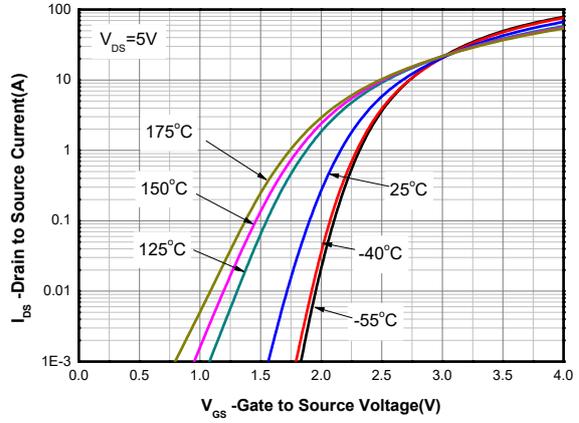
- (1) FR-4 board (38mm × 38mm × t1.6mm, 70 μm Copper) partially covered with copper (645mm² area). The power dissipation P_{DSM} is based on Junction-to-Ambient thermal resistance value and the $T_{J(MAX)}=175^\circ C$. The value is only for reference, any application depends on the user's specific board design.
- (2) The power dissipation P_D is based on $T_{J(MAX)}=175^\circ C$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- (3) Repetitive rating, pulsed, duty cycle ~1%, keep initial $T_J=25^\circ C$, the maximum allowed junction temperature of 175 $^\circ C$.
- (4) The static characteristics are obtained using ~380 μs pulses, duty cycle ~1%.
- (5) The parameter is not subject to production test – verified by design / characterization.

TYPICAL CHARACTERISTICS

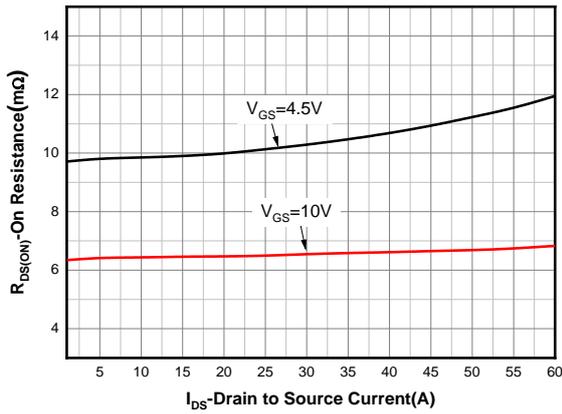
Ta=25°C, unless otherwise noted.



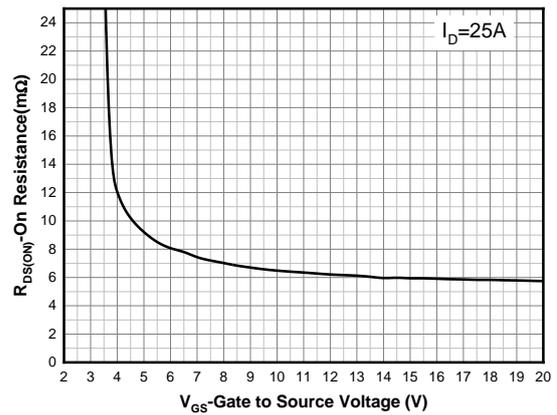
Output Characteristics ⁽⁴⁾



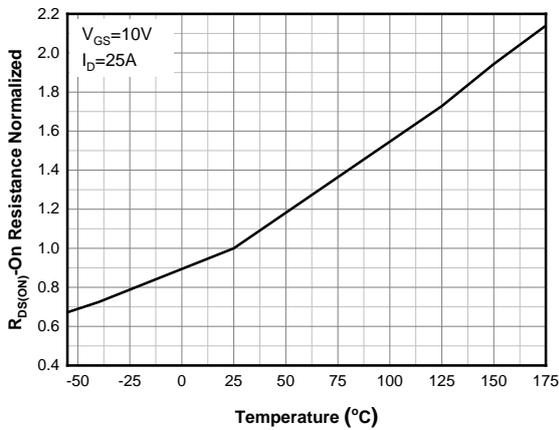
Transfer Characteristics ⁽⁴⁾



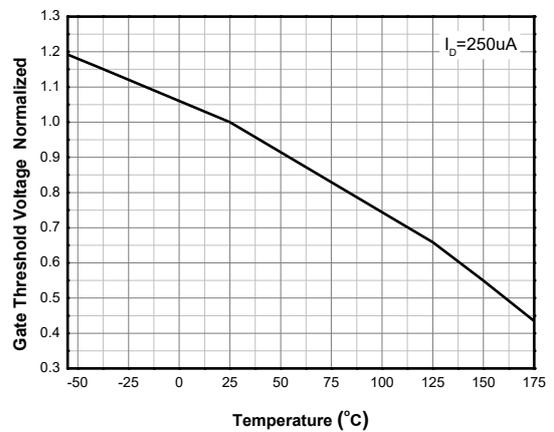
On-Resistance vs. Drain Current ⁽⁴⁾



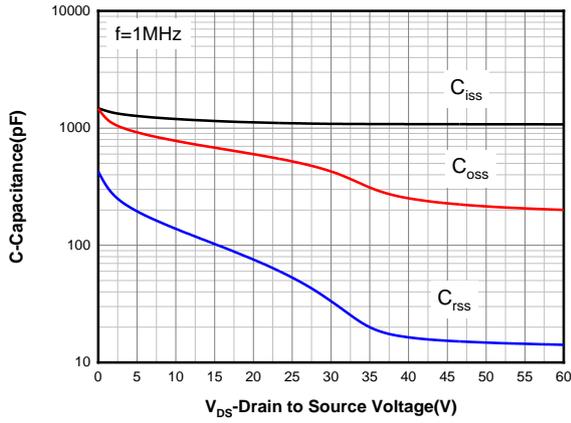
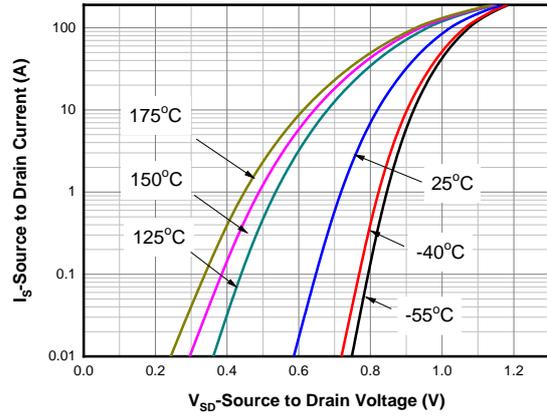
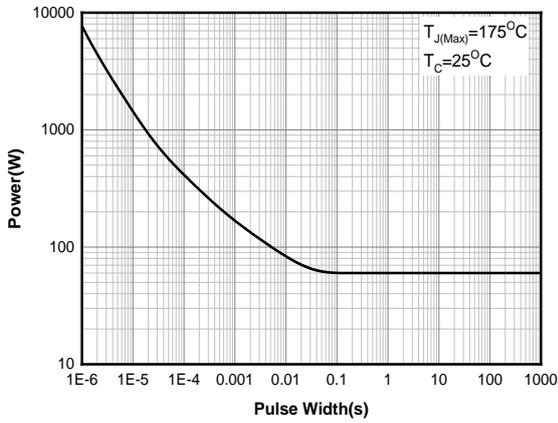
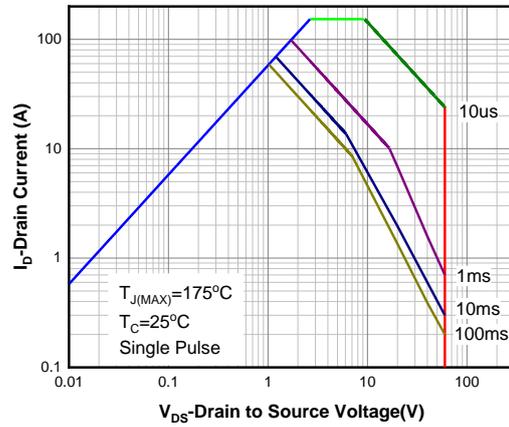
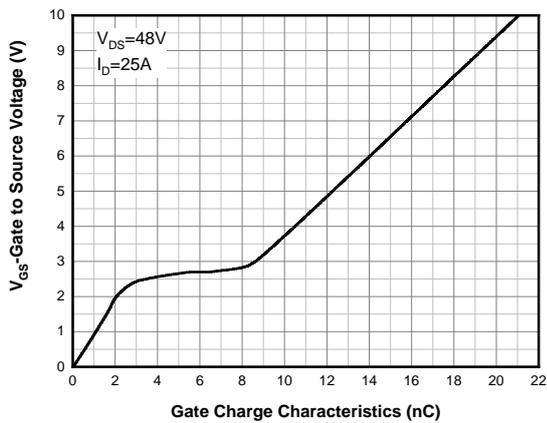
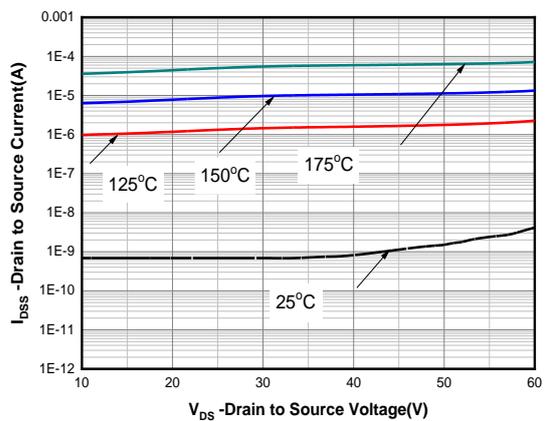
On-Resistance vs. Gate-to-Source Voltage ⁽⁴⁾

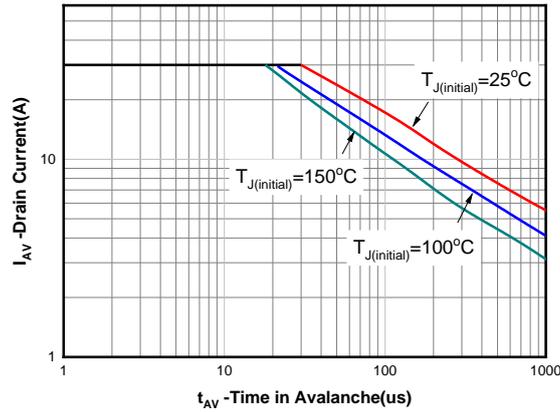
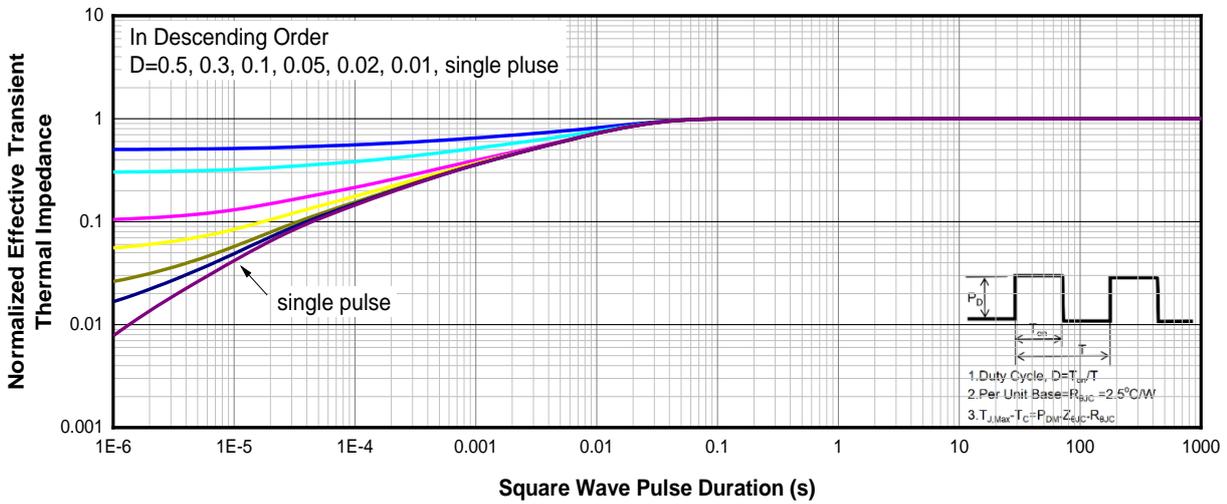
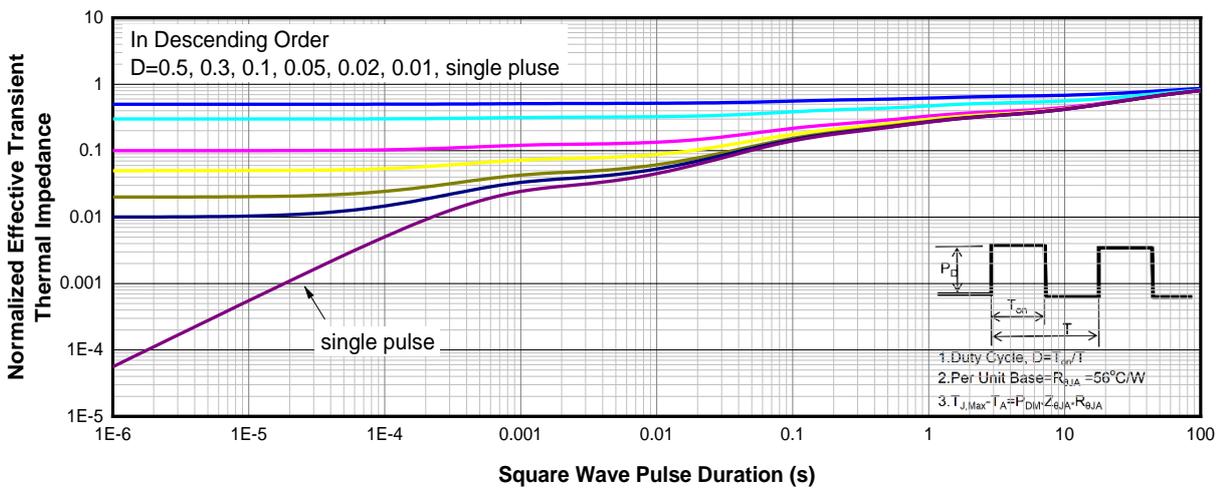


On-Resistance vs. Junction Temperature ⁽⁴⁾



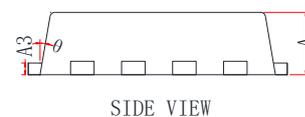
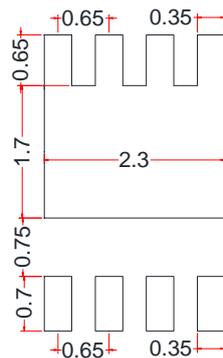
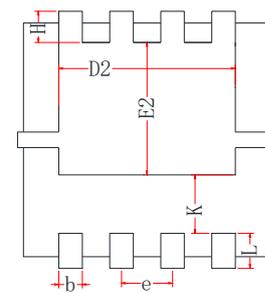
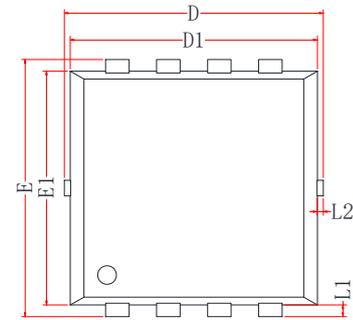
Threshold Voltage vs. Temperature

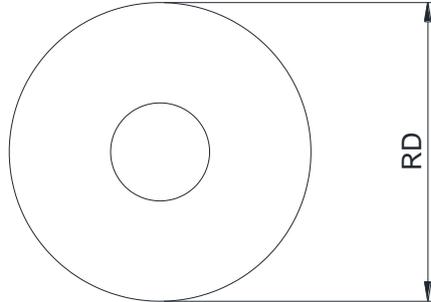
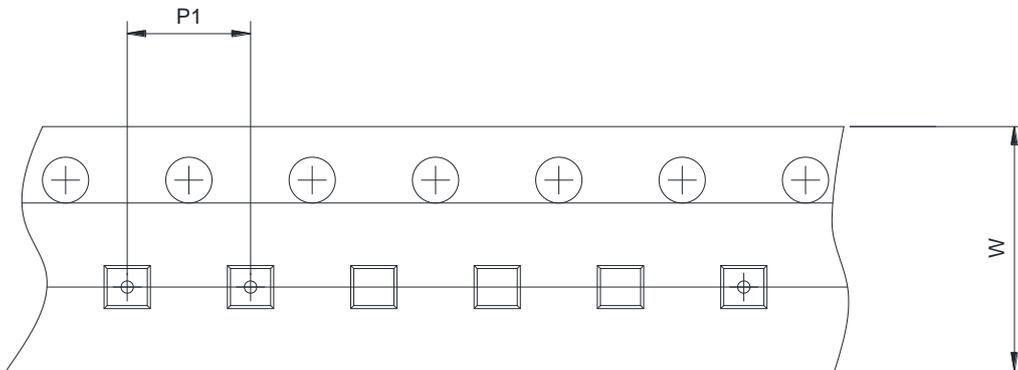
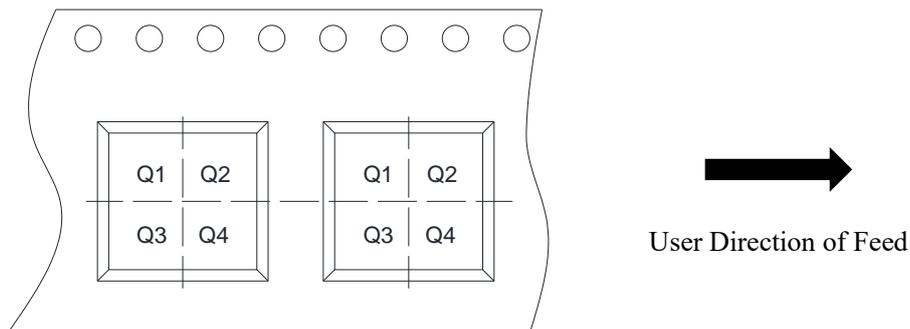

Capacitance

Body Diode Forward Voltage ⁽⁴⁾

Single Pulse power

Safe Operating Area

Gate Charge Characteristics

Drain Current vs. Drain Voltage


Avalanche characteristics

Transient Thermal Response (Junction-to-Case)

Transient Thermal Response (Junction-to-Ambient)

PDFN3333-8L DIMENSIONS
PACKAGE SIZE

Symbol	Min.	Typ.	Max.
A	0.70	0.80	0.90
A3	0.14	0.15	0.20
b	0.25	0.30	0.39
D	3.10	3.30	3.50
D1	3.05	3.15	3.25
D2	2.15	2.25	2.35
e	0.55	0.65	0.75
E	3.10	3.30	3.50
E1	2.90	3.00	3.10
E2	1.60	1.70	1.80
H	0.25	0.40	0.55
K	0.65	0.75	0.85
L	0.30	0.45	0.60
L1	0.05	0.15	0.25
L2	-	-	0.15
θ	8 °	10 °	12 °



TAPE AND REEL INFORMATION
Reel Dimensions

Tape Dimensions

Quadrant Assignments For PIN1 Orientation In Tape


RD	Reel Dimension	<input type="checkbox"/> 7inch	<input checked="" type="checkbox"/> 13inch		
W	Overall width of the carrier tape	<input type="checkbox"/> 8mm	<input checked="" type="checkbox"/> 12mm		
P1	Pitch between successive cavity centers	<input type="checkbox"/> 2mm	<input type="checkbox"/> 4mm	<input checked="" type="checkbox"/> 8mm	
Pin1	Pin1 Quadrant	<input checked="" type="checkbox"/> Q1	<input type="checkbox"/> Q2	<input type="checkbox"/> Q3	<input type="checkbox"/> Q4

ORDERING INFORMATION

TYPE NUMBER	PACKAGE	PACKING
SNM068R2DRAQ-8/TR	PDFN3333-8L	Tape and reel

PDFN3333-8L is packed with 5000 pieces/disc in braided packaging.

Important statement

SIT reserves the right to change the above-mentioned information without prior notice.

REVISION HISTORY

Version number	Datasheet status	Revision date
V1.0	Initial version.	July 2024